

**ABSTRACT OF THE DISCLOSURE**

A method for integrating a system on an isolation layer.  
A first isolation substrate including a first circuit deposition  
region and a first substrate-combining region, and a second  
5 isolation substrate including a second circuit deposition  
region and a second substrate-combining region are provided.  
Next, a first circuit and a second circuit are respectively  
formed on the first circuit deposition region and the second  
circuit deposition region. Next, substrate-connecting elements  
10 are formed to connect the first substrate-combining region to  
the second substrate-combining region. Finally, electrical  
connecting elements are formed to electrically connect the first  
circuit and the second circuit.